

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3096496

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHE-YI HUNG	09/23/2014
	CHIEN-JU LEE	09/23/2014
	HENG-YIN CHEN	09/23/2014
RECEIVING PARTY DATA		
Name:	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE	
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State/Country:	TAIWAN	
Postal Code:	31040	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14527776	
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NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	11/06/2014	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS,

- | | |
|------------------|-----------------|
| 1. Che-Yi Hung | 2. Chien-Ju Lee |
| 3. Heng-Yin Chen | |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **TOUCH PANEL AND SENSING METHOD THEREOF**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Che Yi Hung
Sole or First Joint Inventor: Che-Yi Hung

Date: 2014. 9. 23

Signature: Chien-Ju Lee
Second Joint Inventor (if any): Chien-Ju Lee

Date: 2014. 9. 23

Signature: Heng-Yin Chen
Third Joint Inventor (if any): Heng-Yin Chen

Date: 2014. 9. 23